DOCUMENT CHANGE REQUEST

DCR number 1567

Changes required for: General

Originator: Steve Thacker

Date: 2024/10/21

Date sent: 2023/04/03

Organisation: ESCC Executive Secretariat

Status: IMPLEMENTED

Title:	Evaluation Test Programme For Integrated Circuits: Monolithic And Multichip Microcircuits, Wire-		
Number:	2269000	Issue:	7

Other documents affected:

9000-12

Page:

See original specs above & Mark-ups attached

Paragraph:

See below for details plus Mark-ups attached

Original wording:

As per current specs above

Proposed wording:

ESCC 9000:
Changes resulting from review of the contents of newly published ESCC 9030 & 2269030 vs 9000: see attached for change details (with all changes highlighted yellow):

Title page & Para. 1.1: ref to solder Ball Bonded is removed and with non-organic substrate is added to Flip-Chip bullet (to clarify the different to ESCC9030)

Para. 2.1, 4.2.1(b-v): Add reference to ESCC 22500

Para. 3: Amend definitions to be consistent with ESCC9030/2269030 and clarify the difference to ESCC9030.

Para. 4.5: In 3rd sub-para, replace ceramic body by non-organic substrate

Para. 2.2 & 4.6: add ref to ECSS-Q-ST-60 Class 1 in 3rd sub-para.

Para. 5.3.1, 5.3.2, 5.3.5, 8.4(b)&(e), 9.6, Charts F2A/F2B/F4A/F4B,: replace Flip-Chip Pull-Off test by Bond Shear (Flip-Chip) (M2011 Cond F)

Para. 3, 5.3.2: change solder balls and balls to be bumps.

Para. 8.1: add ref for M2010 Condition A (Class level S) and delete ref to M2032.

Para. 8.2: add refs for M2032 class H and M2017 Class H, & M2013 & M2014.

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Other changes made for correction, consistency and clarification:
Paras. 1.1, 2.1, 5.3.3, 5.3.4, 5.3.5, 5.3.6, 5.3.8, 5.3.9, 8.2, add chart bookmarks

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ESCC 2269000:
Changes resulting from review of the contents of newly published ESCC 9030 & 2269030 vs 2269000: see attached for change details (with all changes highlighted yellow):

Technical changes (ref 2269030 contents):
Title page: ref to solder Ball Bonded is removed and NON-ORGANIC SUBSTRATE is added.

Para. 3: definitions made consistent with 2269030 & 9000

Para. 8.3.2.2: 2nd sentence (on extra test samples) is removed

Paras 8.3.3.2 & 8.3.3.3: (SEE & DD radiation tests) are added.

Para. 8.3.6.3: IEC reference is deleted.

Other changes:
Paras: 2.1, 2.2, 4, 4.1, 4.2, 5.1, 6.5, 6.7, 6.10, 7, 8.1, 8.3.1, 8.3.2.1, 8.3.2.6, 8.3.4, 8.3.4.4, 8.3.4.7, 8.3.4.8, 8.3.4.9, 8.3.5.1, 8.3.5.2.1, 8.3.5.2.2, 8.3.5.3.1, 8.3.5.3.3, 8.3.5.4, 8.3.7.1, 8.4.4, 9.1, 9.2, 9.10, 9.11, 9.12, 9.15, 9.16, 9.16.2, 9.16.4, Charts IA IB IC II III IV, add chart bookmarks

Specific other changes:
All Chart references; Devices renamed as components;solder ball corrected to bump.

Missing requirements added: Para. 4.2, 8.3.4.8, 8.3.4.9, 8.3.4.10, 8.3.5.3.3, 8.4.4, 8.4.5.

Para. 6.5. External visual based on 9000 (not 20500)

Para. 6.7 Xray based on 9000 (not 20900)

Para. 8.3.4.4 Add-on components are included in (b)

Para. 8.3.4.9 modified for all terminal types (in Para. 8.2.4.10)

Para. 8.2.5.2.1 & 8.3.5.2.2, DPA note added

Justification:

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To make ESCC 9000 & 2269000 consistent with the contents of newly published ESCC9030 & 2269030 (as required by the 9000P Working Group) as well as for the purposes of correction & clarification.

Attachments:

escc9000iss_draft_12a_in_review.docx, escc9000iss12_draft_c_(with_final_dcr_changes).docx, escc2269000iss8_draft_c_(with_final_dcr_changes).docx, escc2269000iss_draft_8a_in_review.docx

Modifications:

For ESCC 9000 issue 11:
See attached Draft 12C with highlighted changes:
- Green highlights: per PSWG conclusion
- Blue highlights: minor additional editorial changes
- Yellow highlight are the original DCR changes

PSWG change details:
Para. 3 modify the definitions of:
- Wire bonded Integrated Circuit
- Flip-Chip Integrated Circuit

Paras. 3, 4.6, 5.1.1, 5.3.2, 8.4(c), Chart F2A, Chart F3A, Chart F4A
Redefine Add-on Components to be applicable to both Wire bonded Integrated Circuits and Flip-Chip Integrated Circuits

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For ESCC 2269000 issue 7:
See attached Draft 8C with highlighted changes:
- Green highlights: per PSWG conclusion
- Yellow highlight are the original DCR changes

PSWG change details:
Para. 3 modify the definitions of:
- Wire bonded Integrated Circuit
- Flip-Chip Integrated Circuit
- Add-on Components

Para. 8.3.5.3.1: add Constant Acceleration test (after Vibration) as specified in ESCC9000 Chart F4A.

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Approval signature:

Date signed: